



IC TEST SYSTEM



LANGER IC scanner

with ICR near-field microprobes

(ICR probes)



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IC scanner	1. IC scanner	***
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ICS 105	IC scanner ICS 105 Image: Comparison of the scanner ICS 105 Image: Compa	
	Connected with DUT at spectrum analyser Ground plane	page 4
FLS 102	User interface FLS 102 Spectrum analyser for monitoring DUT at universal holder	page 5
FLS 106	Scanner FLS 106 IC User Interface Power supply DUT at Spectrum analyser	
	for DUT universal holder for monitoring	page 6/7



The IC scanner can be adapted with different ICR probes to measure E- and H-near fields. The probes can be moved above the chip surface in all three axes and around the z-axis.

The scanner allows the user to check the position of the probe tip visually through a video microscope.

The scanner is controlled via PC with the ChipScan-Scanner software.

Axes	x	У	Z	α-rotation
Max. measuring range	50 mm	50 mm	50 mm	+/- 180°
Accuracy	10 µm	10 µm	10 µm	1°
Repeatability	+/- 1 μm	+/- 1 μm	+/- 1 μm	+/- 1°
Speed	2 mm/s	2 mm/s	2 mm/s	45°/s
Control	USB			
Supply voltage	110 / 230 V			
Dimensions / total weight	(350 x 400 x 420) mm / 23 kg			

Software:	 ChipScan-Scanner zero position, manual or script-based probe movement reading the data from a spectrum analyser visualisation of the measuring results in 2D or 3D output as csv and image files
Optional accessories:	- UH-DUT universal holder for receiving the electronics
Scope of delivery:	 ICS 105 IC scanner ICR near-field microprobes for E and H fields Video microscope with holder GND 25 ground plane ChipScan-Scanner software Flight case

Application:

- Surface scans over ICs in accordance with IEC61967-3
- Volume scans over ICs
- PIN scans

System component parts:

- 4-axis positioning system
- ICR near-field microprobes for E and H fields (type ICR)
- Video microscope
- Ground plane (type GND 25)
- ChipScan-Scanner control and measurement software

Properties:

The IC scanner can be adapted with different ICR probes to measure Eand H-near fields. The probes can be moved above the chip surface in all three axes and around the z-axis.

The scanner allows the user to check the position of the probe tip visually through a video microscope.

The scanner is controlled via PC with the ChipScan-Scanner software.



Axes	x	У	z	α-rotation
Max measuring range	200 mm	200 mm	50 mm	+/- 180°
Accuracy	20 µm	20 µm	20 µm	1°
Repeatability	+/- 20µm	+/- 20µm	+/- 20µm	+/- 1°
Speed	65 mm/s	65 mm/s	65 mm/s	90°/s
Control USB				
Supply voltage	110 / 230 V			
Dimensions / total weight	(325 x 450 x 450) mm / 12 kg			

Software:	ChipScan-Scanner - zero position, manual or script-based probe movement - reading the data from a spectrum analyser - visualisation of the measuring results in 2D or 3D - output as csv and image files
Optional accessories:	- UH-DUT universal holder for receiving the electronics
Scope of delivery:	 FLS 102 IC scanner ICR near-field microprobes for E and H fields Video inspection microscope with holder GND 25 ground plane ChipScan-Scanner software

FLS 106 PCB	1. IC scanner 1.2 Scanner types	
Application: - Surface scans ove - Volume scans ove	er PCBs	
 System component 3-axis positioning XF, RF, LF near-find the customer's Universal PCB hotomore ChipScan-Scannet and measurement 	system eld probes choice Ider er control	

Properties:

The scanner is controlled with the ChipScan-Scanner software via a PC. This software lets the user read out the measured data via a spectrum analyser, present this graphically in 2D or 3D as well as store and output this in a CSV file all at the same time.

The "collision protection" software features:

• protects the probe head against destruction should it touch the DUT during a vertical approach

• measure below the safe height

Axes	X	У	Z		
Max. measuring range	600 mm	400 mm	125 mm		
Accuracy	10 µm	10 µm	10 µm		
Repeatability	+/- 20 μm	+/- 20 μm	+/- 20 μm		
Speed	50 mm/s	50 mm/s	25 mm/s		
Control	USB	USB			
Supply voltage	110 / 230 V	110 / 230 V			
Dimensions / total weight	(1030 x 775 x 990	(1030 x 775 x 990) mm / 75 kg			

Software:	ChipScan-Scanner - zero position, manual or script-based probe movement - reading the data from a spectrum analyser - visualisation of the measuring results in 2D or 3D - output as csv and image files
optinal Accessories:	- SX, XF, RF, LF near-field probes of the customer's choice
Scope of delivery:	- FLS 106 PCB IC scanner
	- UH-DUT universal holder for receiving the electronics
	- ChipScan-Scanner software
	The FLS 106 PCB can be upgraded to a FLS 106 IC.

page 6

FLS 106 IC	1. IC scanner 1.2 Scanner types		page 7
 Application: Surface scans ov in accordance wit Volume scans ov PIN scans System compone 4-axis positioning ICR near-field min for E and H fields Universal DUT ho Video microscope ChipScan-Scanne and measuremen 	h IEC61967-3 er ICs nts: system croprobes (type ICR) older e er control	<image/>	

Properties:

The IC scanner can take up ICR near-field micro-probes for H- and E-field measurements and move them to any circuit of the electronic system.

The probes can be moved above the chip surface in all three axes and can be around the z-axis. The scanner allows the user to check the position of the probe tip visually through a video microscope. The scanner is controlled via PC with the ChipScan-Scanner software.

Axes	x	У	z	α-rotation
Max. measuring range	600 mm	400 mm	125 mm	+/- 180°
Accuracy	10 µm	10 µm	10 µm	1°
Repeatability	+/- 20 μm	+/- 20 µm	+/- 20 μm	+/- 1°
Speed	50 mm/s	50 mm/s	25 mm/s	90°/s
Control	USB			
Supply voltage	110 / 230 V			
Dimensions / total weight	(1030 x 775 x 990) mm / 75 kg			

Software:	 ChipScan-Scanner zero position, manual or script-based probe movement reading the data from a spectrum analyser visualisation of the measuring results in 2D or 3D output as csv and image files
optinal Accessories:	- GND 25 ground plane for IC measurement IEC 61967-3
Scope of delivery:	 FLS 106 IC scanner ICR near-field microprobes for E and H-fields Video microscope with holder UH-DUT universal holder for receiving the electronics ChipScan-Scanner software

UH-DUT	1. IC scannerImage: Scanner1.3 Ground plane universal holderpage 8				
	Top view of the universal holder with DUT				
Properties: The UH-DUT ground fixed on the FLS sca the DUT to be meas fastened with severa An adapter is used t UH-DUT on an ICS allows the user to ta ments over the IC of ve DUT board.	anner so that ured can be al claws. o fix the scanner and ke measure-				
Order destination					
UH-DUT Universal holder Thanks to its dimens breadboard design, ferent sizes can be a	DUT's of dif-	Distance - mm Board thickness - 8 mm 20,10	210		
Claw fasteners (01 These fasteners are the DUT and mainta distance between th universal holder. The fastened to the UH I screws.	used to fix in a defined e DUT and e claws are	Distance - m	m)2		



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IC scanner 1.5 Measurement of the radiated emissions

above TEM cell print or IC on a PCB





Test setup of IC Scanner FLS 102 with an universal PCB holder (UH-DUT).

A circular solid state circuit board is mounted on the PCB holder and fixed with claw fasteners.



TEM Cell prints can be fixed on the ground plane GND 25.



Small PCB applications are controled and fixed by an adapter with claw fasteners.

ChipScan	2. Control and operating software
	2.1 User interface



The IC scanner from Langer EMV-Technik is operated and controlled with the modular "ChipScan" program system. The device manager initialises the connected measuring and control devices when the program is started. After this the measurement data ranges can be set for the spectrum analyser and the positioning system via the program's user interface. The command control set (script) is now started to execute the measuring algorithms. All measurements are carried out automatically. The measured data can be displayed in the visualisation area in real time.

User interface when the program is started:



Graphical User Interface (GUI) of the modular "ChipScan" program system

Areas of the user interface:

- Menu bar
- 2 Spectrum analyser setup to set up the device via the user interface
- Graphic joystick to manually guide the positioning device (x, y, z, α) (Options: setting the step width in μm and degrees)
- Spectrum analyser measure for individual measurements
- Script window and start button for scripts
 (Command scripts for mover control and measuring algorithms)
- 6 Output window for program messages and alphanumeric script output
- Visualisation range for 2D and 3D graphics of the measuring results (Options in the View and Visualisation menu)

ChipScan	 Control and operating software User interface 	page 12

Device initialisation (device manager):

The device manager initialises all connected devices when the program is started. (Menu – Devices – Device Manager – Scan – OK)

The result of the link set-up is displayed as a program message.

The spectrum analyser operating parameters are set for the respective measurement. The settings carried out on the user interface are sent to the spectrum analyser by the "set" command.

Spectrum Analyzer Setup Center [MHz] 1500.0 Atn [dB] 5 RBW [kHz] 1000.0 Ref [dBm] -20 Average 10 Span [MHz] 3000.0 STime [mS] 60 VBW [kHz] 100.0 X/div [dB] 10 Auto - Sweep Time Auto - Attenuator Auto - RBW Frequency Auto - VBW Frequency Mode Average Mode Average Mode Average Mode Average Mode Average Mode Mode Mode Mode Mode Mode Mode Mod	Graph 100.0 MHz Update < Spectrum Analyzer 1 Steps Measure Auto Set before Me
Open Devicemanager.	
Langer EMV Technik ChipScan 3D v 1.40	
Figure 2: Spectrum analyser set-up data	

Control of the positioning device (x, y, z, α)

The near-field microprobe is manually moved to the initial measurement position with the graphic joystick.



The command control set (script) for the scheduled measurement is chosen in the script window and started. The measurement process is executed in accordance with the script as a point, line or volume scan.

ChipScan	2. Control and operating software 2.1 User interfaceImage: 13			
	ement algorithms are: scans through a user definedset o	f control commands (scr	ipts)	
Following measu - point scan - line scan - surface scan - volume scan	rement algorithms are ready to ι	ISE:		
The measured spe	easurement results ectra are displayed three-dimension eent. The user may choose betweer res.	-		
 3D-graphics can 3D-graphics can 3D-graphics can graphics 	ot measured curves be viewed from any angle be zoomed and shifted be converted into two-dimensional	File Devices View Visualization Curves 3D Curves 3D Surface	Sequences Options Help Alt-1 Alt-2 Alt-3 Alt-4	
spectrum - Export of individu Export of 2D- and	n of the measured frequency al sweeps to Excel (Take plot) d 3D-graphics to Excel ction (*.png, *.jpg, *.tiff)	Volume Points Volume Contours Volume Isosurface Volume Image View Options	Alt-7	
		Figure 5: Display of the m	neasurement results	
	ager in the "Visualisation" menu a s ay be altered in its type of display:	et of measured curves r	may be selected.	
34.09 34.66 32.71 32.77	001 AF 640 Here			
-erat Level (dBuV) -axe	aming the last	- www.sh		

WWWWWWWWWWWW

2100

1802

2401

2701

3000

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304.5

Figure 6: 2D-view of a set ot measured curves

004

903.5

Frequency (MHz)

40.8

ChipScan	2. Control and operating software 2.1 User interface		page 14	
Measurei	Measurement of the radiated emission of the test IC with the surface scan method IEC 61967-3 using near-field microprobes			
The measuring spati ned. At every point the sion up to 3 (6) GHz Fig. 7: Scan volume and me (menu: View – Volume	he radiated emis- is meassured.			
Visualization of the sion over the scanne high level). The disp be moved with the c Fig. 8: Magnetic field of mea played as colorcut (menu: View – Volum	ed IC-area (red: layed surface can ursor in z-axis. asuring range dis-			
Additionally the colo be spinned by 90° at over the IC. Fig. E9 equidistant snap sho near field Fig. 9: Magnetic field ge displayed as equi (menu: View – Volum	nd be dragged shows several ots of the magnetic of measuring ran- distant colorcuts			
Spatial visualization field as ISO-surfaces magnetic field intens colors. Fig. 10: Magnetic fiel range displayed as IS (menu: View-Volume	s displays equal sities with different d of measuring SO-surfaces			

IEC 61967	2. Control and operating software	- Wi
	2.2 Surface Scan Methods with near-field microprobes	pa

The surface scan method is a technique of measuring the radiated emissions from ICs by evaluating the near-field electromagnetic component over the surface of the package or the die in the frequency range up to 3 or 6 GHz. In order to perform such an evaluation, the IC is scanned by near-field microprobe.

This method is capable of providing a detailed pattern of the emission sources within the DUT with a spatial resolution that depends from both the precision of the mechanical positioning system and the employed near-field micro probe. Our technology allows spatial resolution of ICR HH 150 of 100 μ m and mechanical precision of ICS 103/105 and FLS 102 up to 10 μ m.

In example 1 the surface scan method is used on a mobile phone. Measurement is a "Volume Scan" of an IC area of mobile phone.

Example 1: Volume Scan of a IC area on a mobile phone





Fig. E2: Zoomed measuring IC area



IEC 61967	2. Control and operating software 2.2 Surface Scan Methods with near-field microprobesImage: 16				
Board CB 0706 via means of a PC-cor DUT surface accor	The DUT has to be mounted onto the ground plane GND 25. It is adapted to the Connection Board CB 0706 via sixty point connector. The near-field microprobe is mechanically scanned by means of a PC-controlled probe positioning system. In particular, the probe is scanned over the DUT surface according to a programmed pattern while an automatic acquisition system enables the control of the scan parameters.				
Measuring range a are defined as inpu the program.		Z Brnny Case	1000 (1950) -76.2 -76.2 -75.2 -75.2		
Fig. E4: Scan volume and me (menu: View – Volum		X (mm)	37.6		
Visualization of ma on over the scanne high level). The dis can be moved in z-	ed IC-area (red: played surface		4.est bine -92.6 -72.9		
Fig. E5: Magnetic field of mea played as colorcut (menu: View – Volum Colorcut Alt-6 and Alt	e Contours and		-78.1		
Spatial visualization tic field as ISO-surf constant magnetic with different colors	faces shows the field intensities	t ormet and the second se	4244 (1004) - 42.4 - 72.4 - 72.5		
Fig, E6: Magnetic field of mea played as ISO-surface (menu: View-Volume	es		.751		

IC Emission

Control and operating software 3 Measurement of the radiated emission of the test IC



with high resolution and accuracy



IC Emission2. Control and operating software 2.4 Measurement of the radiated emission of the test DIEImage 18					
with high resolution a	with high resolution and accuracy				
IC Scanner System	FLS 102 with DIE test adapter				
Surface scan with nea microprobe above the					
3D Volume scan of the field area above the D	e magnetic near NE				



ICR probes	R probes3. ICR near-field microprobes 3.1 Probe types' overviewImage 20			
Probe types	Inside diameter	Orientation	Measuring range	
ICR HV 100-27	— 100 µm	H vertical	1.5 MHz to 6 GHz	
ICR HV 100-6		vertiour	2.5 MHz to 6 GHz	
ICR HH 100-27	100 μm	H horizontal	1.5 MHz to 6 GHz	
ICR HH 100-6	100 μπ	- Tonzontar	2.5 MHz to 6 GHz	
ICR HV 150-27	450		1.5 MHz to 6 GHz	
ICR HV 150-6	150 μm	H O vertical	2.5 MHz to 6 GHz	
ICR HH 150-27	150 μm	H horizontal	1.5 MHz to 6 GHz	
ICR HH 150-6	100 μπ	nonzontar	2.5 MHz to 6 GHz	
ICR HV 250-75	250		500 kHz to 2 GHz	
ICR HV 250-6	250 μm	H overtical	2.5 MHz to 6 GHz	
ICR HH 250-75	250 μm	H horizontal	500 kHz to 2 GHz	
ICR HH 250-6	200 μπ	- Tonzontar	2.5 MHz to 6 GHz	
ICR HV 500-75		1	200 kHz to 1 GHz	
ICR HV 500-6	500 μm	H O vertical	2 MHz to 6 GHz	
ICR HH 500-75	500 μm	H horizontal	200 kHz to 1 GHz	
ICR HH 500-6	ουο μπ	i i i i i i i i i i i i i i i i i i i	2 MHz to 6 GHz	
ICR E 150	150 µm x 35 µm	E horizontal	7 MHz to 3 GHz	



ICR probes	3. ICR near-field microprobes 3.2 Design and designations	page 22
probe can thus be Probe head The probe head is microprobe. Horizontal and ver	rudes from the amplifier case The ICR positioned optically above the DUT. the sensor element of the near-field tical probe heads are available with neters to measure the magnetic field.	ICR probe
The probe head g and measures hig The probe head is positioning relativ	ning with an IC scanner) Jets closer to the measurement object Jher signal intensities. Is more easily visible to allow its exact the to the object to be measured.	Probe head
		Probe head Resin
Refer to the figure ping and handling packing the probe	ipping and handling cover on the right on how to remove the ship- cover. Refit the protective cover before away.	2. Pull off from above Shipping and handling cover
tee. The BT 706 st (9 V, 100 mA). Frequency range: Connection: SMA Power supply: 12 V Note: The bias tee from tegrated voltage st		Bias-Tee BT 706 12 V/DC 12 V/DC





ICR probes	3. ICR near-field microprobesImage: 253.3 Probe characteristics ICR HH 100page 25
Probes	Characteristic
H 100µm	76 Sean in Subline Seann Oler In -26 -36 -40
H field probes ICR HH 100-27 1.5 MHz - 6 GHz ICR HH 100-6 2.5 MHz - 6 GHz	Level (dBµV)
 Resolution 70 µm Horizontal measuring coil Inside diameter 100 µm Screened measuring coil 	1 Plot = 0,03 mm (30 µm)
Transverse profile Position z of the HH probe variable relative to the strip line SL	Stripline
Frequency response of the HH probe measured at minimum and maximum	Stripline



ICR probes	3. ICR near-field mic 3.3 Probe characteristic		27
Probes	Characteristic		
H 150µm	-16.40 -33.00 -33.00 -20.00 -2		
H field probes ICR HH 150-27 1.5 MHz - 6 GHz ICR HH 150-6	Lovel (GSLV) 50.50 50.50 -01.73 -05.00 -01.27 0 0 0 0 23 -00 -01.27 0 0 0 23		
 2.5 MHz - 6 GHz Resolution 100 μm Horizontal measuring coil Inside diameter 150 μm Screened measuring coil 	1 Plot = 0,03 mm (30 μm) Section insister latue Cense (end) Section insister latue Gener (end) Section insister latue Gener (end) Section insister latue Gener (end) <	X/dv (dl) 10 • CAurage Los Reset	
Transverse profile Position z of the HH probe variable relative to the strip line SL	Stripline	ICR HH 150 on 20 µm strip line Transverse profile, distance 10 µm, frequency 500 MHz, step width 20 µ	m
Frequency response of the HH probe measured at minimum and maximum	Stripline	ICR HH 150-27 and HH 150-6 Frequency response on 20 µm strip line, distance 20 µm HH150-6 MAX HH150-27 MAX HH150-27 MAX GHz 6	

ICR probes	3. ICR near-field mid 3.3 Probe characteristic	•	page 28
Probes	Characteristic		
H-field probes	Stanger EMV Technik ChipScan 30 Ele Deklas vav geuellator Seganos Optors Bilt Stand Level (dBroy 313) Level (dBroy 313)		Control of
ICR HV 250-75 500 kHz - 2 GHz	200 ¹ 000	a a Ma Pers	
ICR HV 250-6 2.5 MHz - 6 GHz	artz Frinquency (M		net sur
 Resolution 110 µm Vertical measuring coil Inside diameter 250 µm Screened measuring coil 	Spectrum matters ford, Derauf and (1990) - And (11) - Hendland, (20) Derauf and (1990) - Manager (1990) -	1 Plot = 0,1 mm (100 µm)	
Transverse profile	Stripline	ICR HV 250 on 20 µm strip line Transverse profile, distance 20 µm, frequency	500 MHz
Position z of the HV probe variable relative to the strip line SL	₽ ₽ ₽	-20 -40 MAX MAX	
	-0,8 -0,4 0 0,4 0,8 z	-60 -1,2 -0,6 0 0,6 1,2	z [mm]
Frequency response of the HV probe measured at minimum and maximum	Stripline	ICR HV 250-75 and HV 250-6 Frequency response on 20 µm strip line, distance dB -20 -40 -40 -60 -80 0 3 G	ce 20 μm

ICR probes	3. ICR near-field mic 3.3 Probe characteristic	
Probes	Characteristic	
	Bie Destors View Uncellation Securices Options	
H-field probes	Mo Koo Level (dBuV) es N	101
ICR HH 250-75 500 kHz - 2 GHz	41 49 20.79 20.09 27.36	Inc.3 Inc.2 Flots Inc.2 Flots
ICR HH 250-6 2.5 MHz - 6 GHz	2017 446.3 670 at	2243 2007 cy (MHz) 1335 1847 1779 2000 301 2007
- Resolution 150 µm		1 Plot = 0,03 mm (30 μm)
- Horizontal measuring coil	Contraction of the second s	All NO Array Contracts
- Inside diameter 250 μm	G Add Sweighter T Add Alfordater T Add Starburgeter	
- Screened measuring coil	Some of the second states and the second states and states an	
Transverse profile Position z of the HH probe variable relative to the strip line SL	Stripline	ICR HH 250 on 20 µm strip line Transverse profile, distance 20 µm, frequency 500 MHz
Frequency response of the HH probe measured at minimum and maximum	Stripline	ICR HH 250-75 and HH 250-6 Frequency response on 20 µm strip line, distance 20 µm dB -20 -40 -40 -40 -40 -40 -40 -40 -40 -40 -4

1.4 ICR probes	3. ICR near-field microprobesImage: Compage C	- 30
Probes	Characteristic	
	Langer EMV Technik ChipSean 3	-
H-field probes	ervel tolbuv) mine armet armet	
ICR HV 500-75 200 kHz - 1 GHz	ana ana ana ana ana ana ana ana ana ana	
ICR HV 500-6 2 MHz - 6 GHz	ALLS Freitbuncy (MHS) ALLS FREI FREI FREI FREI FREI FREI FREI FREI	
 Resolution 300 µm Vertical measuring coil Inside diameter 500 µm 	Sectors inter	
 Screened measuring coil 	Shah the pitest	E .
Transverse profile Position z of the HV probe variable relative to the strip line SL	Stripline	
Frequency response of the HV probe measured at minimum and maximum	Stripline HODE MAX MIN Stripline Stripline MIN Stripline Stripline MIN Stripline MIN Stripline S	

ICR probes	3. ICR near-field microp 3.3 Probe characteristics IC		page 31
Probes	Characteristic		
H S00µm	Bir Devices View Youwitzeten Separates Options Bills		Serve III Constructions Network III Construction Serve III (Serve 2, or 1997)
H-field probes ICR HH 500-75 200 kHz - 1 GHz	410 410 10 10 10 10 10 10 10 10 10 10 10 10 1	in the second se	
ICR HH 500-6 2 MHz - 6 GHz	Frequency M407	1 Plot = 0,03 mm (30 µm)	Nat Sold
 Resolution 300 µm Horizontal measuring coil Inside diameter 500 µm Screened measuring coil 	Spectrami Andyren (smap) Contex (smap) Spec(Alla) (2000.0 mm)Ad) (1 mm)Ad((1 mm)Alla) (100.0	- Sage	 - -
Transverse profile Position z of the HH probe variable relative to the strip line SL		MAX	20 MHz
Frequency response of the HH probe measured at minimum and maximum	Stripline G G G G G G G G G G G G G	HH500-6 MAX HH500-75 MAX	



The characteristics show the dependence of the probe position s (x, y, z) relative to the space, probe angle α and signal frequency f of the ICR E 150 E-field microprobe.



above Stripline analogue to IEC 61967-6

IC Scanner System ICS 103/105

In this application the scanner is used as the probe test setup to calibrate the near field microprobes.

The near-field microprobes are calibrated above a stripline.



The calibration data is measured above the stripline. The measurement takes place analogue to norm IEC 61967-6.



Reference level 100 dBµV

For practical measurement the calibration data for the individual probe is used. The measured curve is corrected by the calibration curve.

The measurement above the stripline with calibration results in a horizontal line. So the measurements with different mic-roprobes are compareable.



IC Test System	4. Instructions
	4.1 Safety and warranty



-This product complies with the requirements of the following European Community Directives: 89/336/EC (Electromagnetic Compatibility) and 73/23/EC (Low Voltage) as amended by 93/68/EC (CE-Marking).

Safety precautions

When using the near-field microprobes please observe the following basic safety instructions to protect the near-field microprobes against the risk of injury:

- Read and comply with the operating manual.
- Keep the operating manual in a safe place for subsequent use.
- Follow the safety instructions and warnings on the unit.
- Always perform a visual check of the near-field microprobes before use.
- Keep hands away from probe tips.
- Do not leave the IC scanner with near-field microprobes unsupervised.
- Read the explanation of the symbols on the probe case and in the operating manual.
- The near-field micro probe has been designed for IC measurements of magnetic or electric field. Any other use is not permitted.
- Do not switch the IC scanner with ICR probes on until it has been completely assembled.
- Damaged connection cables are extremely dangerous!

Safety symbol 🖊



This CAUTION symbol indicates a potentially hazardous situation which could result in minor or moderate injury or damage to the near-field micro probes if ignored. This symbol indicates that the operator must refer to an explanation in the operating instructions.

The warranty is only valid under the following conditions:

- the near-field microprobes have been treated properly,
- the operating instructions have been followed,
- for maintenance only original parts have to be used,
- external components like video microscope, spectrum analyzer, motor control unit seperate warranty terms of the relevant manufacturer apply.

The warranty is forfeited if:

- attempts have been made to repair the near-field microprobe,
- the near-field microprobe has been altered,
- the near-field micro probe has been used incorrectly.

IC Test System	4. Instructions4.2 Standard operating procedure	bage 35
used for delivery. One probe case o	croprobes' (ICR probes') original packaging is a special case that is al contains 1 to 3 ICR probes according to the options ordered. 's provided with a protective cap.	SO
- There is a Cautic - The protective ca	on symbol on the probe's protective cap. up is labelled:	
"Never, unde	er any circumstances, touch the probe tip!"	
- Always insert the locked in place.	ICR probe into a probe holder or IC scanner with the probe's cap	
	nolder or IC scanner manually to its maximum height position on inserting the ICR probe.	
_	protective cap just before you start to prepare an automatic measurer y true when approaching the DUT starting position.	nent.
	holder or IC scanner manually to its maximum height position on end of each automatic measurement or if it is in the idle state.	
Then fit and lock f	the ICR probe's protective cap.	
Proceed accordin > Bring the probe > Fit and lock the or an IC scanne		
> Place the remo	oved ICR probe into the probe case.	



C - Storge

Dipl.-Ing. C. Stange Development

LANGER EMV-Technik GmbH Nöthnitzer Hang 31 DE-01728 Bannewitz

This calibration is in compliance with the International EMC Standard of ICs IEC 61967. Supporting Documentation relative to traceability is on file and available for examination upon request.

This certificate shall not be reproduced except in full without the written approval of Langer EMV-Technik.